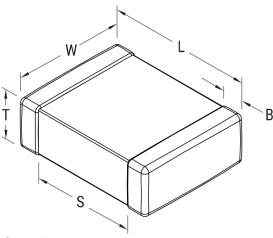


C0805C332KAGECTU

Aliases (C0805C332KAGEC7800)

ESD SMD Comm C0G, Ceramic, 3300 pF, 10%, 250 VDC, C0G, SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I, 0805



Click here for the 3D model.

Dimensions	
Chip Size	0805
L	2mm +/-0.2mm
W	1.25mm +/-0.2mm
Т	0.78mm +/-0.10mm
S	0.75mm MIN
В	0.5mm +/-0.25mm

Packaging Specifications		
Packaging	T&R, 180mm, Paper Tape	
Packaging Quantity	4000	

General Information	
Series	ESD SMD Comm COG
Style	SMD Chip
Description	SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I
Features	Temperature Stable, Low ESR, Class I
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Component Weight	11 mg
Shelf Life	78 Weeks
MSL	1

Specifications	
Specifications	
Capacitance	3300 pF
Measurement Condition	1 kHz 1.0 Vrms
Capacitance Tolerance	10%
Voltage DC	250 VDC
ESD Level per AEC-Q200	16,000 V ESD Level
Dielectric Withstanding Voltage	625 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1 kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOhms

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